



#### 30V N-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub> T <sub>A</sub> = +25°C
	$760$ m $\Omega$ @ V <sub>GS</sub> = 4.5V	0.65A
30V	930mΩ @ V <sub>GS</sub> = 2.5V	0.58A
	1500mΩ @ V <sub>GS</sub> = 1.8V	0.45A

## **Description**

This MOSFET has been designed to minimize the on-state resistance (R<sub>DS(on)</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## **Applications**

- Load switch
- Portable applications
- **Power Management Functions**

### **Features**

- 0.4mm ultra low profile package for thin application
- 0.48mm<sup>2</sup> package footprint, 16 times smaller than SOT23
- Low V<sub>GS(th)</sub>, can be driven directly from a battery
- Low R<sub>DS(on)</sub>
- **ESD Protected**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

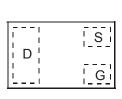
### **Mechanical Data**

- Case: X2-DFN0806-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.00043 grams (approximate)

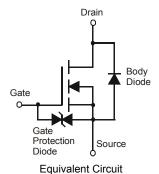












## **Ordering Information** (Note 4)

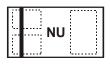
Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN3900UFA-7B	NU	7	8	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**

DMN3900UFA-7B



Top View Bar Denotes Gate and Source Side

NU = Product Type Marking Code



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	30	V
Gate-Source Voltage			V <sub>GSS</sub>	±8	V
		(Note 6)	I <sub>D</sub>	0.65	A
Continuous Drain Current	V <sub>GS</sub> = 4.5V	T <sub>A</sub> = +70°C (Note 6)		0.52	
		(Note 5)		0.55	
Pulsed Drain Current		(Note 7)	I <sub>DM</sub>	2.5	

### Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Power Dissipation	(Note 6)	ם	490	- mW	
Power Dissipation	(Note 5)	P <sub>D</sub>	390		
Thermal Decistance, Junction to Ambient	(Note 6)	0	255	°C/W	
Thermal Resistance, Junction to Ambient	(Note 5)	R <sub>0JA</sub>	327		
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

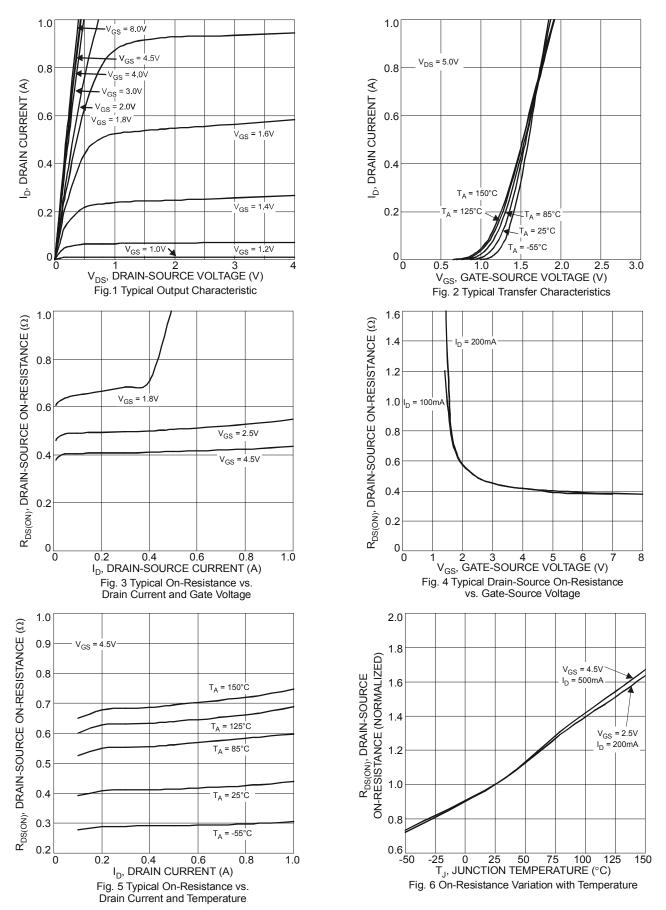
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μΑ	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	3	μΑ	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.45	_	0.95	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
			400	760		$V_{GS}$ = 4.5V, $I_{D}$ = 200mA	
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	_	480	930	mΩ	$V_{GS} = 2.5V, I_D = 100mA$	
			617	1500		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 75mA	
Forward Transfer Admittance	Y <sub>fs</sub>	40	_	_	mS	V <sub>DS</sub> = 3V, I <sub>D</sub> = 10mA	
Diode Forward Voltage (Note 8)	V <sub>SD</sub>	_	0.7	1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 300mA	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>	1	42.2	_	pF	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Output Capacitance	Coss	1	4.5	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	3,4	_	pF	1 - 1.00012	
Gate Resistance	Rg	_	468	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge	Qg	_	0.7	_	nC		
Gate-Source Charge	$Q_{gs}$	_	0.11	_	nC	$V_{GS} = 4.5V, V_{DS} = 15V,$ $I_{D} = 200 \text{mA}$	
Gate-Drain Charge	Q <sub>gd</sub>	_	0.15	_	nC		
Turn-On Delay Time	t <sub>D(on)</sub>	_	10.5	_	ns		
Turn-On Rise Time	t <sub>r</sub>	_	7.8	_	ns	V <sub>DS</sub> = 10V, I <sub>D</sub> = 200mA	
Turn-Off Delay Time	t <sub>D(off)</sub>	_	80.6	_	ns	$V_{GS} = 4.5V$ , $R_G = 6\Omega$	
Turn-Off Fall Time	t <sub>f</sub>	_	23.4	_	ns		

Notes:

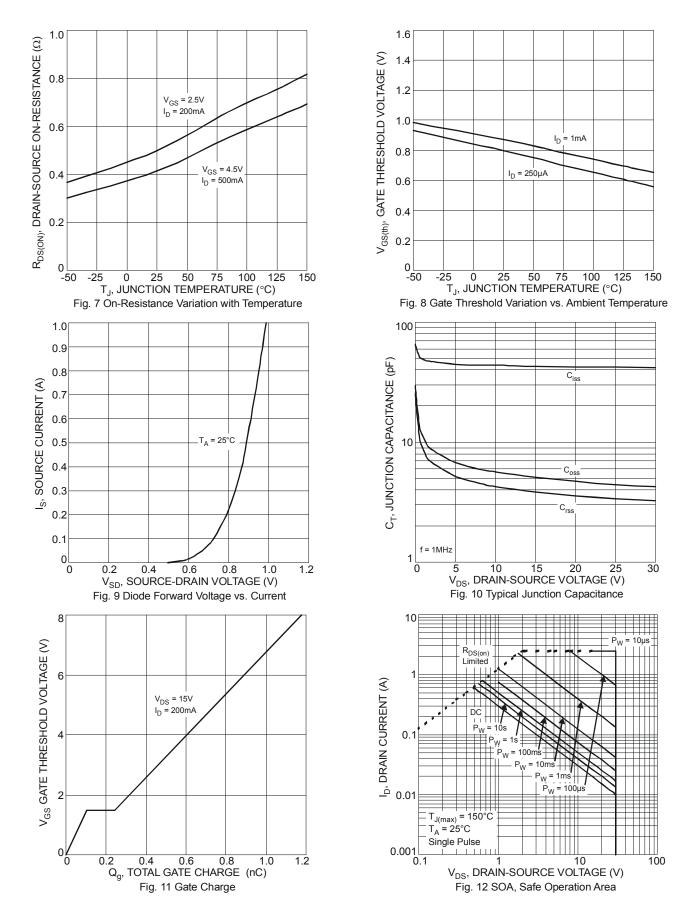
- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- 6. Device mounted on FR-4 PCB, with minimum recommended pad layout, except the device measured at t ≤ 10 sec.
  7. Device mounted on minimum recommended pad layout test board, 10µs pulse duty cycle = 1%.
  8. Short duration pulse test used to minimize self-heating effect.

- 9. Guaranteed by design. Not subject to production testing

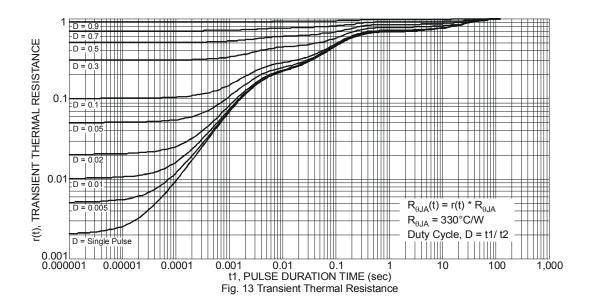






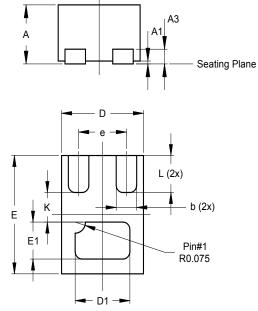






## **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

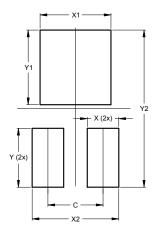


	X2-DFN0806-3					
Dim	Min	Max	Тур			
Α	0.375	0.40	0.39			
A1	0	0.05	0.02			
A3	-	-	0.10			
b	0.10	0.20	0.15			
D	0.55	0.65	0.60			
D1	0.35	0.45	0.40			
Е	0.75	0.85	0.80			
E1	0.20	0.30	0.25			
е	-	-	0.35			
K	-	-	0.20			
Ĺ	0.20	0.30	0.25			
All Dimensions in mm						



### Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)			
С	0.350			
Х	0.200			
X1	0.450			
X2	0.550			
Y	0.375			
Y1	0.475			
Y2	1.000			

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